

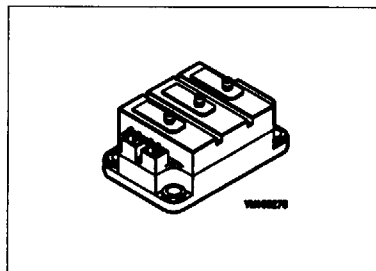
IGBT Module® 100gb16a doc

$V_{CE} = 1600 \text{ V}$

$I_C = 2 \times 135 \text{ A at } T_C = 25^\circ\text{C}$

$I_C = 2 \times 100 \text{ A at } T_C = 80^\circ\text{C}$

- Power module
- Half-bridge
- Including fast free-wheel diodes
- Package with insulated metal base plate



Half-bridge			
Type	Ordering code	Type	Ordering code
BSM 100 GB 160D	C67076-A2112-A2		

Maximum Ratings

Parameter	Symbol	Values	Unit
Collector emitter voltage	V_{CE}	1600	V
Collector gate voltage, $R_{GE} = 20 \text{ k}\Omega$	V_{CGR}	1600	
Gate-Emitter voltage	V_{GE}	± 20	
Continuous collector current	I_C	$T_C = 25^\circ\text{C}$	A
		$T_C = 80^\circ\text{C}$	
Pulsed collector current	$I_C \text{ puls}$	$T_C = 25^\circ\text{C}$	A
		$T_C = 80^\circ\text{C}$	
Operating and storage temperature range	T_j, T_{stg}	-55...+150	$^\circ\text{C}$
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	1000	W
Thermal resistance, chip-case	R_{thJC}	≤ 0.13	K/W
Insulation test voltage ¹⁾ , $t = 1 \text{ min.}$	V_{is}	4000	V _{ac}
Creepage distance	-	20	mm
Clearance	-	11	
DIN humidity category, DIN 40 040	-	F	--
IEC climatic category, DIN IEC 68-1	-	55/150/56	

¹⁾Insulation test voltage between collector and metal base plate referred to standard climate 23/50 in acc. with DIN 50 014, IEC, para. 492.1.

Electrical Characteristics

Parameter and conditions at $T_j = 25^\circ\text{C}$, unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Static Characteristics

Collector-emitter breakdown voltage $V_{GE}=0, I_C=2\text{mA}$	$V_{(BR)CES}$	1600	-	-	V
Gate threshold voltage $V_{GE}=V_{CE}, I_C=8\text{mA}$	$V_{GE(th)}$	4.8	5.5	6.2	
Collector-emitter saturation voltage $V_{GE}=15\text{V}, I_C=100\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$ $T_j = 150^\circ\text{C}$	$V_{CE(sat)}$	--	3.5 4.2 4.4	--	
Zero gate voltage collector current $V_{CE}=1600\text{V}, V_{GE}=0\text{V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{CES}	--	1000 4500	--	
Gate-emitter leakage current $V_{GE}=25\text{V}, V_{CE}=0\text{V}$	I_{CES}	--	--	100	nA

AC Characteristics

Forward transconductance $V_{CE}=20\text{V}, I_C=100\text{A}$	g_{fs}	36	--	--	S
Input capacitance $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{iss}	--	16	--	nF
Output capacitance $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{oss}	--	1.3	--	
Reverse transfer capacitance $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{rss}	--	0.5	--	

Parameter and conditions at $T_j = 25^\circ\text{C}$, unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Switching Characteristics, Inductive Load**at $T_j=125^\circ\text{C}$**

Turn on delay time $V_{CC}=1200\text{V}, V_{GE}=+15\text{V}, I_C=100\text{ A}$ $R_{G(on)}=33\Omega$	$t_{d(on)}$	--	0.85	--	μs
Rise time $V_{CC}=1200\text{V}, V_{GE}=+15\text{V}, I_C=100\text{ A}$ $R_{G(on)}=33\Omega$	t_r	--	0.3	--	μs
Turn off delay time $V_{CC}=1200\text{V}, V_{GE}=-15\text{V}, I_C=100\text{ A}$ $R_{G(off)}=3.3\Omega$	$t_{d(off)}$	--	2.5	--	μs
Fall time $V_{CC}=1200\text{V}, V_{GE}=-15\text{V}, I_C=100\text{ A}$ $R_{G(off)}=3.3\Omega$	t_f	--	0.15	--	μs

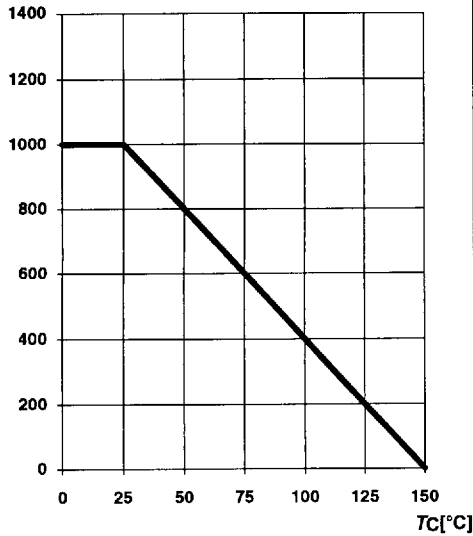
Free-Wheel Diode

Diode forward voltage $I_F=100\text{ A}, V_{GE}=0\text{V}$ $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$	V_F	--	4.2 3.8	--	V
Reverse recovery time $I_F=100\text{ A}, V_R=-1200\text{V}$ $V_{GE}=0\text{V}, di_F/dt=-1000\text{A}/\mu\text{s}$ $T_j=125^\circ\text{C}$	t_{rr}	--	0.5	--	μs
Reverse recovery Charge $I_F=100\text{ A}, V_R=-1200\text{V}$ $V_{GE}=0\text{V}, di_F/dt=-1000\text{A}/\mu\text{s}$ $T_j=125^\circ\text{C}$	Q_{rr}	--	50	--	μC
Thermal resistance Chip-Case	R_{thJC}	--	--	0.5	K/W

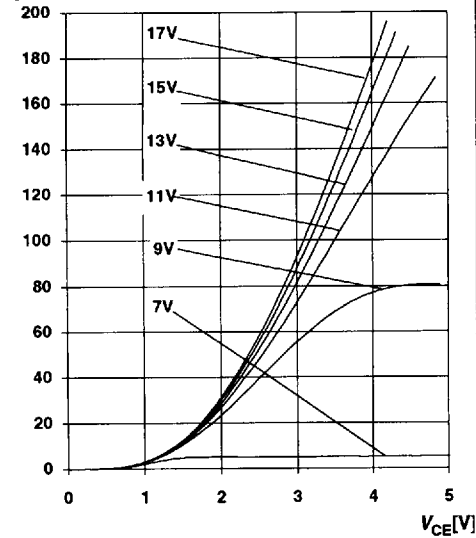
Power dissipation

$$P_{\text{tot}} = f(T_C)$$

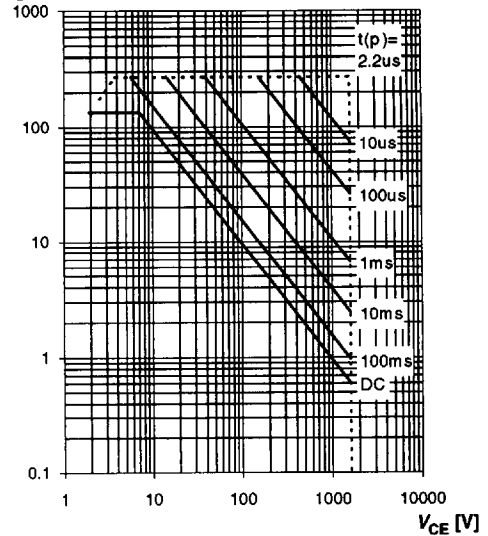
$$P_{\text{tot}} [\text{W}]$$

**Typ output characteristics $I_C = f(V_{CE})$** parameter: $t_p = 80 \mu\text{s}$; $T_J = 25^{\circ}\text{C}$

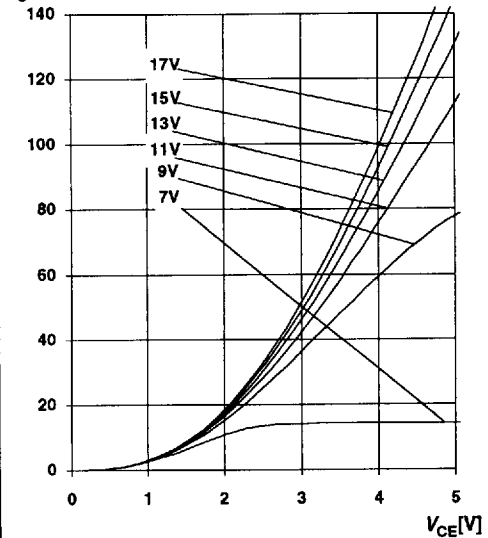
$$I_C [\text{A}]$$

**Safe operating area $I_C = f(V_{CE})$** parameter: single pulse, $T_C = 25^{\circ}\text{C}$, $T_J \leq 150^{\circ}\text{C}$

$$I_C [\text{A}]$$

**Typ output characteristics $I_C = f(V_{CE})$** parameter: $t_p = 80 \mu\text{s}$; $T_J < 125^{\circ}\text{C}$

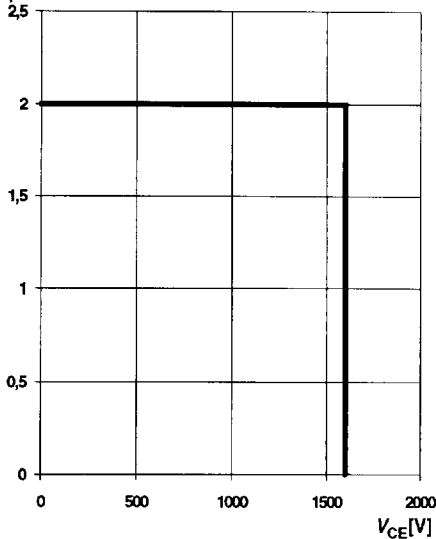
$$I_C [\text{A}]$$



Reverse biased safe operating area

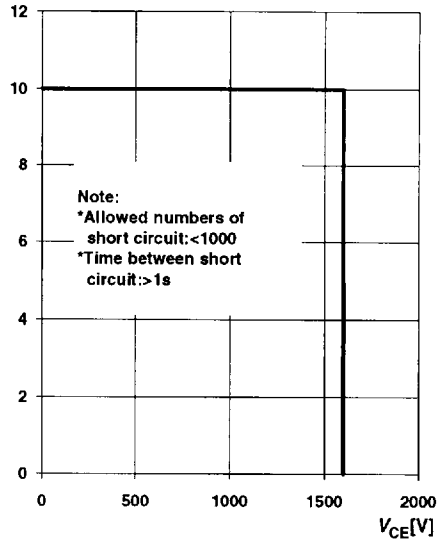
$I_C = f(V_{CE})$, parameter: $T_J = 150^\circ\text{C}$
 $V_{GE} = 15\text{V}$, $R_{g(\text{off})} = 3.3\Omega$

$I_{C\text{puls}}/I_C$

**Safe operating area, SHORT CIRCUIT**

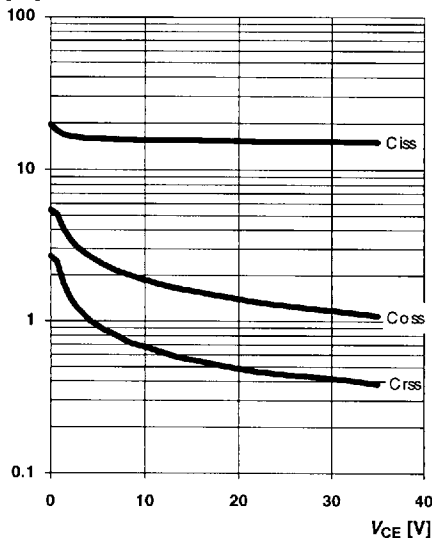
$I_C = f(V_{CE})$, $V_{GE} = \pm 15\text{V}$, $T_J \leq 150^\circ\text{C}$
 $t_{sc} \leq 10\mu\text{s}$, $L < 50\text{nH}$

I_{CSC}/I_{CN}

**Typ. capacitances**

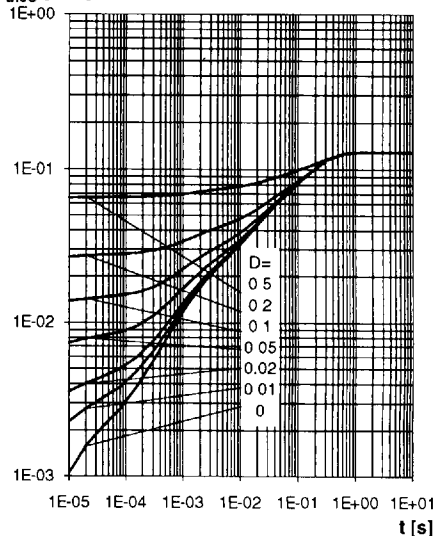
Parameter: $V_{GE} = 0$, $f = 1\text{ MHz}$

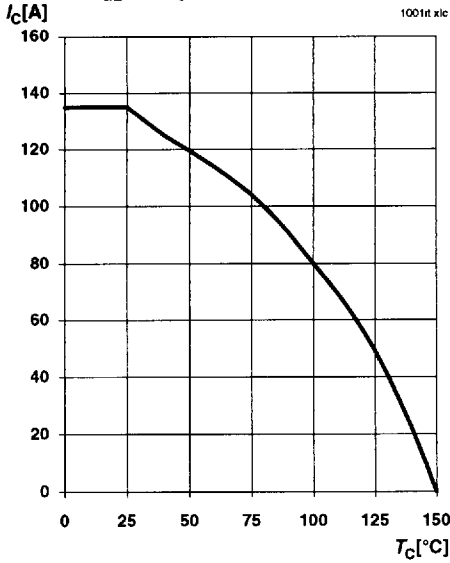
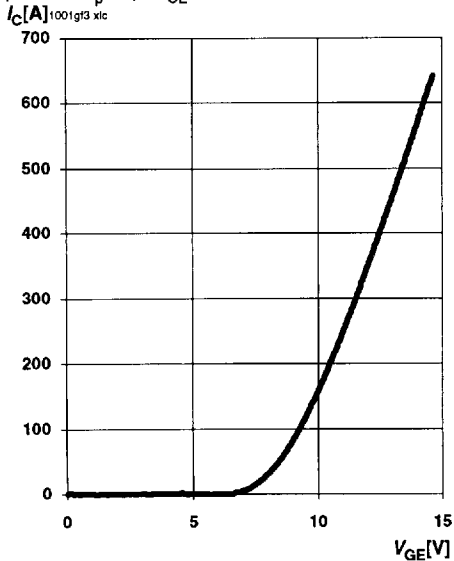
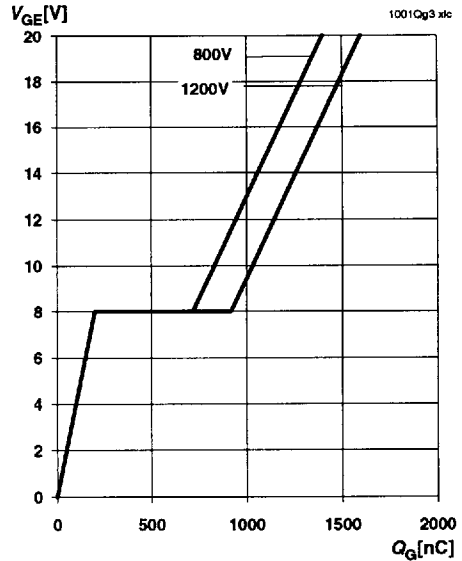
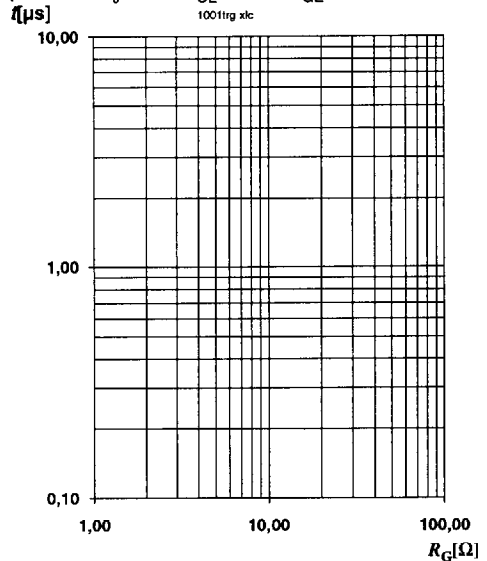
$C[\text{nF}]$

**Transient thermal impedance**

$Z_{thJC} = f(t_p)$, parameter: $D = t_p/T$

$Z_{thJC} [\text{K/W}]$



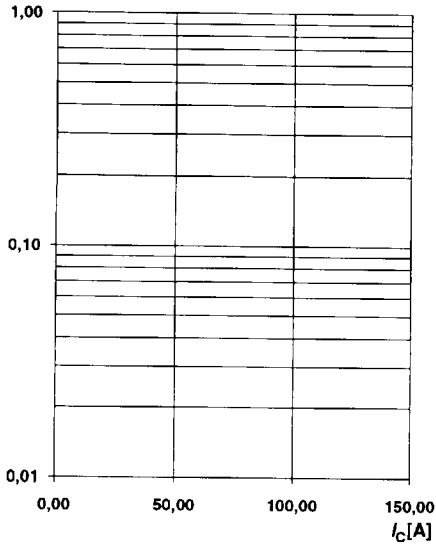
Collector current $I_C = f(T_C)$ parameter: $V_{GE} \geq 15V, T_J = 150^\circ$ **Typ. transfer characteristics $I_C = f(V_{GE})$** parameter: $t_p = 80 \mu s, V_{CE} = 20V$ **Typ. gate charge, $V_{GE} = f(Q_G)$** **Typ. switching time $t_s = f(R_G)$ Inductive load**parameter: $T_J = 125^\circ C, V_{CE} = 1200V, V_{GE} = \pm 15V$ 

Typ. switching time $t = f(I_C)$

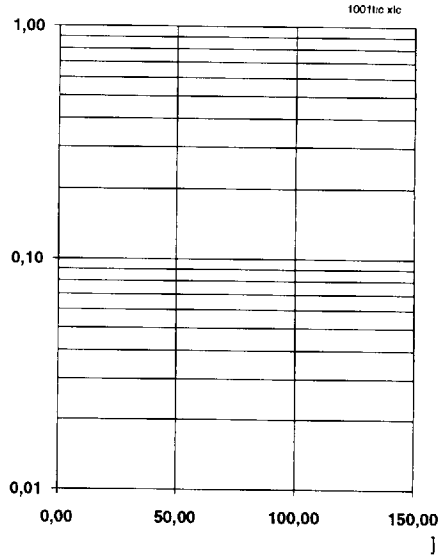
Inductive load, parameter: $T_J = 125^\circ\text{C}$

$V_{CE} = 1200\text{V}$, $V_{GE} = \pm 15\text{V}$, $R_{Gon} = 47\Omega$, $R_{Goff} = 3.3\Omega$

$t_f [\mu\text{s}]$



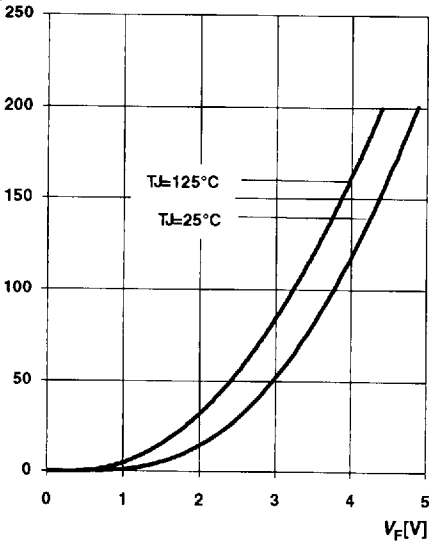
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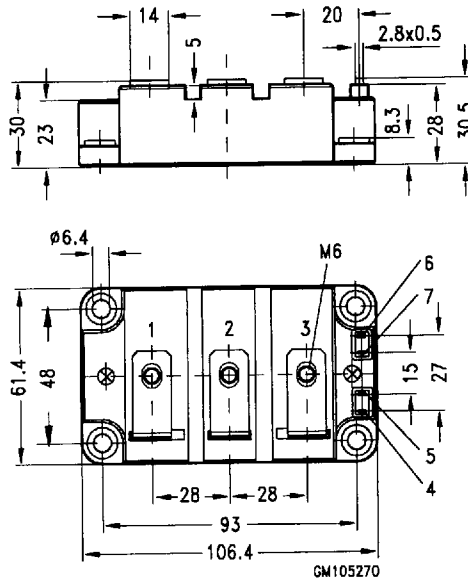
Forward characteristics of fast recovery reverse diode

$I_F = f(V_F)$, parameter: T_J

$I_C [\text{A}]$



Package Outlines and Configuration



Circuit

